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1µA Ultra-Tiny Shunt Voltage Reference

MAX6069

General Description

The MAX6069 ultra-low-power shunt references are ideal for space-critical and low-power applications. They are offered in a 4-bump wafer-level package (WLP), and the minimum operating current is guaranteed to be less than 1μ A. These references feature low temperature coefficients of less than 20ppm/°C and initial accuracy of better than 0.2%.

Available with +1.25V, +2.048V, +2.5V, and 3V output voltages, these references can be used as lowerpower, higher-precision upgrades to the ICL8069, LM385, LT1004, and LM4040 in much smaller packages. Two grades are available: A and B. The A grade features a temperature coefficient of 25ppm/°C over the extended temperature range of -40°C to +85°C, with an initial accuracy of 0.2%. Grade B features a temperature coefficient of 50ppm/°C over the extended temperature range of -40°C to +85°C, with an initial accuracy of 0.2%. Grade B features a temperature range of -40°C to +85°C, with an initial accuracy of 0.5%. Their tiny wafer-level packages make these references ideal for equipment with very small form factors.

Applications

- Portable Sensors
- Portable Meters
- Precision Regulators
- A/D and D/A Converters
- 4mA–20mA Loop-Powered Sensors

Benefits and Features

- Wide Operating Current Range: 1µA to 2mA
- 0.88mm x 1.16mm, 4-Bump WLP
- Initial Voltage Accuracy: 0.2%
- Temperature Coefficient: 20ppm/°C (max)
- Temperature Range: -40°C to +125°C
- Factory-Trimmed Output Voltages: +1.25V, +2.048V, +2.5V, +3.0V
- Functionally Equivalent to the MAX6006/MAX6007/ MAX6008/MAX6009

Ordering Information appears at end of data sheet.

Simplified Block Diagram



1µA Ultra-Tiny Shunt Voltage Reference

Absolute Maximum Ratings

Operating Current (OUT to GND)20	DmA	Operating Temperature Range40°C to +	125°C
Forward Current (GND to OUT)20	OmA	Storage Temperature Range65°C to +	150°C
Continuous Power Dissipation (Multilayer Board;		Junction Temperature+	150°C
derate 9.75mW/°C above +70°C)780r	mW	Soldering Temperature (reflow)+	260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

WLP

Package Code	W40D1+1			
Outline Number	<u>21-100139</u>			
Land Pattern Number	Refer to Application Note 1891			
Thermal Resistance, Four-Layer Board:				
Junction-to-Ambient (θ _{JA})	102.59°C/W			
Junction-to-Case (θ _{JC})	N/A			

For the latest package outline information and land patterns (footprints), go to <u>www.maximintegrated.com/packages</u>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Electrical Characteristics

 $(T_A = -40^{\circ}C \text{ to } +125^{\circ}C, \text{ unless otherwise noted.}, \text{Typical values are at } T_A = +25^{\circ}C. \text{ (Note 1))}$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
MAX6069A (1.250V)	` 						
Reverse Breakdown Voltage	$V_{R} \qquad \begin{array}{c} T_{A} = +25^{\circ}C, \\ I_{R} = 1.2\mu A \end{array}$	T _Δ = +25°C,	MAX6069AA (0.2%)	1.2475	1.2500	1.2525	V
		I _R = 1.2μA	MAX6069AB (0.5%)	1.2438	1.2500	1.2563	
Minimum Operating Current	I _{RMIN}	V_R change < 0.2% from V_R at I_R = 1.2µA			0.5	1.0	μA
Reverse Breakdown Change with Current		I _R = 1.2μA to 200μA I _R = 200μA to 2mA				1	mV
						2.0	
Reverse Dynamic Impedance		I _R = 1.2µA to 2mA (Note 2)				1.5	Ω
Low-Frequency Noise		I _R = 1.2μA, f = 0.1H		30		µVp-p	

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Electrical Characteristics (continued)

 $(T_A=-40^{\circ}C \text{ to } +125^{\circ}C, \text{ unless otherwise noted.}, Typical values are at T_A = +25^{\circ}C. (Note 1))$

PARAMETER	SYMBOL	cc	NDITIONS	MIN	TYP	MAX	UNITS	
	тс	I _R = 1.2μΑ, MAX6069AA	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$			20	- ppm/°C	
Temperature Coefficient (Note 3)			$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			25		
		I _R = 1.2μΑ, MAX6069AB	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$			50		
			$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			75		
Long-Term Drift		1000h at T _A = +2	5°C		150		ppm	
Thermal Hysteresis (Note 4)					200		ppm	
MAX6069B (2.048V)	1	1		1			1	
		T _A = +25°C,	MAX6069BA (0.2%)	2.0439	2.048	2.0521		
Reverse Breakdown Voltage	V _R	I _R = 1.2μA	MAX6069BB (0.5%)	2.0378	2.048	2.0582	- V	
Minimum Operating Current	I _{RMIN}	V _R change < 0.2%	// % from V _R at I _R = 1.2μA		0.5	1.0	μA	
Reverse Breakdown Change		I _R = 1.2µA to 200	μΑ			1.3		
with Current		$I_{R} = 200 \mu A \text{ to } 2mA$				2.3	mV	
Reverse Dynamic Impedance		I _R = 1.2μA to 2mA (Note 2)				1.8	Ω	
Low-Frequency Noise		I _R = 1.2μA, f = 0.1	1Hz to 10Hz		50		µVp-p	
Temperature Coefficient (Note 3)	тс		Ι _R = 1.2μΑ,	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			20	ppm/°C
Temperature Coefficient (Note 3)		MAX6069BA	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			25	ppm/°C	
Temperature Coefficient (Note 3)		I _R = 1.2µA,	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			50	ppm/°C	
Temperature Coefficient (Note 3)		MAX6069BB	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			75	ppm/°C	
Long-Term Drift		1000h at T _A = +2	5°C		150		ppm	
Thermal Hysteresis (Note 4)					200		ppm	
MAX6069C (2.500V)	1	1		1			1	
		T _A = +25°C,	MAX6069CA (0.2%)	2.4950	2.5000	2.5050		
Reverse Breakdown Voltage	V _R	TA 20 0,	MAX6069CB (0.5%)	2.4875	2.5000	2.5125	V	
Minimum Operating Current	I _{RMIN}	$V_{\rm R}$ change < 0.2% from $V_{\rm R}$ at $I_{\rm R}$ = 1.2µA			0.5	1.0	μA	
Reverse Breakdown Change		$I_{R} = 1.2 \mu A \text{ to } 200 \mu A$ $I_{R} = 200 \mu A \text{ to } 2 m A$				1.5		
with Current						2.5	mV	
Reverse Dynamic Impedance		$I_R = 1.2 \mu A \text{ to } 2 m A$	A (Note 2)			2	Ω	

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Electrical Characteristics (continued)

(T_A=-40°C to +125°C, unless otherwise noted., Typical values are at T_A = +25°C. (Note 1))

PARAMETER	SYMBOL	COI	NDITIONS	MIN	TYP	MAX	UNITS	
Low-Frequency Noise		I _R = 1.2μA, f = 0.1Hz to 10Hz			60		µVp-p	
		I _R = 1.2μΑ, ΜΑΧ6069CA	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			20		
Temperature Coefficient	тс		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			25	- ppm/°C	
(Note 3)		I _R = 1.2μΑ,	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			50		
		MAX6069CB	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			75		
Long-Term Drift		1000h at T _A = +25	°C		150		ppm	
Thermal Hysteresis (Note 4)					200		ppm	
MAX6069D (3.00V)								
Reverse Breakdown Voltage	V _R	T _A = +25°C, I _R = 1.2μA	MAX6069DA (0.2%)	2.9940	3.0000	3.0060	- V	
			MAX6069DB (0.5%)	2.9850	3.0000	3.0150		
Minimum Operating Current	I _{RMIN}	V_R change < 0.2% from V_R at I_R = 1.2µA			0.5	1.0	μA	
Reverse Breakdown		I _R = 1.2μA to 200μA I _R = 200μA to 2mA				1.7	mV	
Change with Current						2.7	mv	
Reverse Dynamic Impedance		I _R = 1.2μA to 2mA	I _R = 1.2µA to 2mA (Note 2)			2.2	Ω	
Low-Frequency Noise		I _R = 1.2μA, f = 0.1	Hz to 10Hz		75		µVp-p	
		I _R = 1.2μA, MAX6069DA	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			20		
Temperature Coefficient (Note 3)	тс		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			25	ppm/°C	
		I _R = 1.2μA, MAX6069DB	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$			50		
			$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			75		
Long-Term Drift		1000h at T _A = +25°C			150		ppm	
Thermal Hysteresis (Note 4)					200		ppm	

Note 1: All units are 100% production tested at T_A = +25°C and are guaranteed by design and characterization for

 $T_A = T_{MIN}$ to T_{MAX} , as specified. **Note 2:** This parameter is guaranteed by the "reverse breakdown change with current" test.

Note 3: TC is measured by the "box" method; i.e., $(V_{MAX} - V_{MIN})/(T_{MAX} - T_{MIN})$. **Note 4:** Thermal hysteresis is defined as the change in the +25°C output voltage after cycling a unit from T_{MIN} to T_{MAX}.

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Typical Operating Characteristics

(T_A = +25°C, unless otherwise noted.)







MAX6069CA PEAK-PEAK OUTPUT VOLTAGE NOISE (0.1Hz to 10Hz)



REVERSE DYNAMIC IMPEDANCE vs. TEMPERATURE (MAX6069CA) 0.3 0.2



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Pin Configuration



Pin Description

PIN	NAME	FUNCTION
A1	OUT	Output Voltage. Bias OUT with a pullup resistor to a potential greater than OUT. Bypass OUT to GND with a 0.01μ F or larger capacitor.
A2	GND	Ground
B1	OUT	Output Voltage. B1 is shorted to A1 internally.
B2	GND	Ground. B2 is shorted to A2 internally.

Detailed Description

The MAX6069 family consists of precision, twoterminal, shunt bandgap voltage references. On-chip, thin-film resistors are laser-trimmed to provide 0.2% output voltage accuracies. Voltages of +1.25V, +2.048V, +2.5V, and +3.0V are available in a space-saving 4-bump WLP.

Applications Information

Output/Load Capacitance

Bypass OUT to GND with a 0.01μ F or larger capacitor. In applications where the load or the supply can experience step changes, additional capacitance will reduce the amount of overshoot (or undershoot) and assist the circuit's transient response.

Output Voltage Hysteresis

Output voltage hysteresis is the change in the output voltage at $T_A = +25^{\circ}$ C before and after the device is cycled over its entire operating temperature range. Hysteresis is caused by differential package stress appearing across the bandgap core transistors. The temperature hysteresis value is typically less than 200ppm.

Turn-On Time

The output capacitance and bias current of the MAX6069 greatly affect turn-on settling time. In the <u>Typical Operating</u> <u>Characteristics</u>, turn-on time is shown with a 10nF output capacitor and a 1.2μ A bias current. Under these conditions, the MAX6069 settles in about 4ms. Settling time linearly decreases in proportion to the circuit's bias current.

Typical Application Circuits

Shunt Regulator Connection

In the typical shunt regulator connection shown here, R_{BIAS} sets the current through the load (I_L) and the current through the shunt regulator(I_R). There are two worst-case situations that R_{BIAS} needs to be sized for:

- 1) R_{BIAS} must be small enough that when V_S (supply voltage) is at its minimum and I_L is at its maximum, I_R is equal to at least the minimum operating current of the shunt regulator.
- 2) R_{BIAS} must be large enough that when V_S is at its maximum and I_L is at its minimum, I_R is < 2mA.



Precision Current Sink



Precision Current Source



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Ordering Information

PART NUMBER	OUTPUT VOLTAGE (V)	INITIAL ACCURACY (%)	TEMP COEFFICIENT (PPM/°C)	PIN-PACKAGE	TOP MARK
MAX6069AAAWS+*	1.250	0.2	20	4 WLP	+AM
MAX6069AAAWS+T*	1.250	0.2	20	4 WLP	+AM
MAX6069ABAWS+*	1.250	0.5	50	4 WLP	+AN
MAX6069ABAWS+T*	1.250	0.5	50	4 WLP	+AN
MAX6069BAAWS+	2.048	0.2	20	4 WLP	+AO
MAX6069BAAWS+T	2.048	0.2	20	4 WLP	+AO
MAX6069BBAWS+*	2.048	0.5	50	4 WLP	+AP
MAX6069BBAWS+T*	2.048	0.5	50	4 WLP	+AP
MAX6069CAAWS+	2.500	0.2	20	4 WLP	+AQ
MAX6069CAAWS+T	2.500	0.2	20	4 WLP	+AQ
MAX6069CBAWS+	2.500	0.5	50	4 WLP	+AR
MAX6069CBAWS+T	2.500	0.5	50	4 WLP	+AR
MAX6069DAAWS+*	3.000	0.2	20	4 WLP	+AS
MAX6069DAAWS+T*	3.000	0.2	20	4 WLP	+AS
MAX6069DBAWS+*	3.000	0.5	50	4 WLP	+AT
MAX6069DBAWS+T*	3.000	0.5	50	4 WLP	+AT

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

*Future product—contact factory for availability.

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Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	6/17	Initial release	—
1	10/21	Updated <i>Electrical Characteristics, Precision Current Source</i> figure, and <i>Ordering Information</i>	3, 4, 7, 8



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